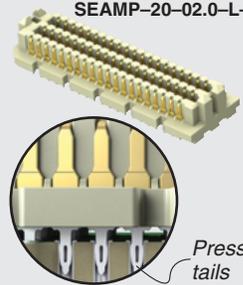




SEAMI-50-11.0-L-10-2-A-K-TR



(1,27 mm) .050"

SEAMP, SEAMI SERIES

HIGH SPEED/HIGH DENSITY OPEN PIN FIELD

Mates with:
SEAF, SEAF-RA-GP

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAMP

Insulator Material: Natural LCP
Contact Material: Copper Alloy
Operating Temp Range: -55°C to +125°C
Current Rating: 2.5 A per pin (6 adjacent pins powered)
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Contact Resistance: 8.7 mΩ
Working Voltage: 215 VAC
RoHS Compliant: Yes

RECOGNITIONS

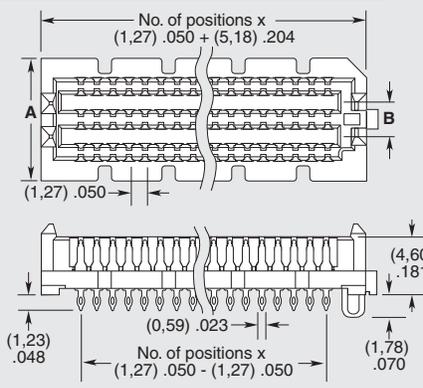
For complete scope of recognitions see www.samtec.com/quality



Note: Compliant pin fixture CAT-SEAMP-XX-XX. Patent Pending.

SEAMP	NO. OF POSITIONS PER ROW	02.0	PLATING OPTION	NO. OF ROWS	OPTION
SEAMP = Press Fit	-10, -20, -30, -40, -50		-L = 10µ" (0,25 µm) Gold on contact area, Matte Tin on tail	-04 = Four Rows	-GP = Guide Post (Mates with SEAF-RA-GP only)
			-S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tail	-06 = Six Rows	-TR = Tape & Reel
				-08 = Eight Rows	
				-10 = Ten Rows	

NO. OF ROWS	A	B
-04	(7,06) .278	(2,54) .100
-06	(9,60) .378	(2,54) .100
-08	(12,14) .478	(5,08) .200
-10	(14,68) .578	(7,62) .300



MATED HEIGHTS*		
SEAMP LEAD STYLE	SEAF LEAD STYLE	
-05.0	-06.0	-06.5
-02.0	7 mm	8 mm 8.5 mm

*Processing conditions will affect mated height.

SEAMP/SEAF-RA	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	11 GHz / 22 Gbps
Differential Pair Signaling	11 GHz / 22 Gbps

*Test board losses de-embedded from performance data. Complete test data available at www.samtec.com?SEAMP or contact sig@samtec.com

Processing: Application tooling and one ton minimum press required. Contact ATG@samtec.com for more information.

Mates with:
SEAF

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAMI

Insulator Material: Black LCP
Contact Material: Copper Alloy
Operating Temp Range: Testing Now!
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Contact Resistance: Testing Now!
Working Voltage: Testing Now!
RoHS Compliant: Yes
Lead-Free Solderable: Yes

ALSO AVAILABLE (MOQ Required)

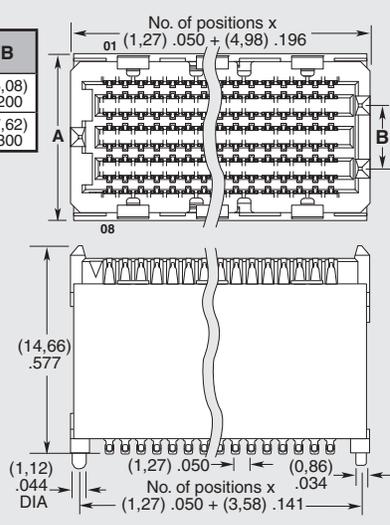
- Other plating options
- 20 & 30 pins per row
- 04 & 06 rows
- Contact Samtec.

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.

SEAMI	NO. PINS PER ROW	11.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	TR
SEAMI = 85Ω tuned	-40, -50		-L = 10µ" (0,25 µm) Gold on contact area, Matte Tin on solder tail	-08 = Eight Rows	-1 = Tin/Lead Alloy Solder Charge	-A = Alignment Pins	-K = Polyimide film Pick & Place Pad	
			-S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on solder tail	-10 = Ten Rows	-2 = Lead-Free Solder Charge			-TR = Tape & Reel

NO. OF ROWS	A	B
-08	(13,41) .528	(5,08) .200
-10	(15,95) .628	(7,62) .300



MATED HEIGHTS*		
SEAMI LEAD STYLE	SEAF LEAD STYLE	
-11.0	-05.0	-06.0 -06.5
-11.0	16 mm	17 mm 17.5 mm

*Processing conditions will affect mated height.

SEAMI/SEAF 16 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	14 GHz / 28 Gbps
Differential Pair Signaling	16.5 GHz / 33 Gbps

*Test board losses de-embedded from performance data. Complete test data available at www.samtec.com?SEAMI or contact sig@samtec.com

28+
Gbps